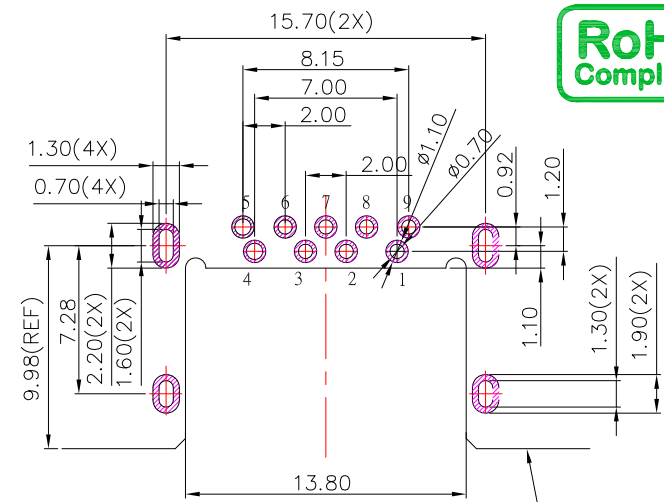
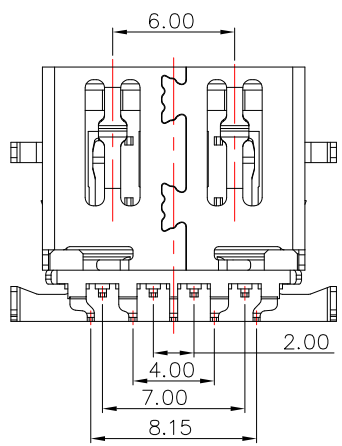
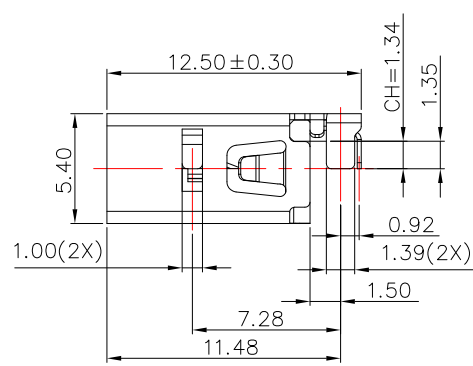
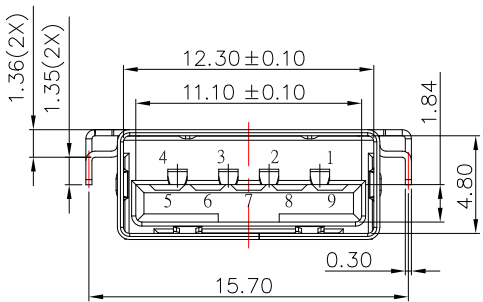
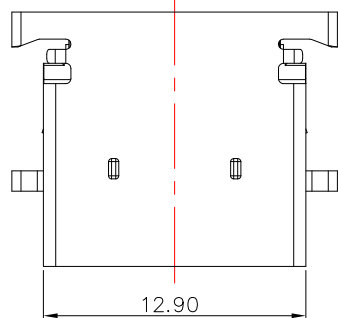




SUA-110E7-30xx-S277

鍍層厚度 : HOUSING :

Blank : 1u"	Blank : Blue
2 : 15u"	K : BLack
3 : 30u"	



RECOMMENDED PCB LAYOUT
TOP VIEW

PCB EDGE

NOTE:

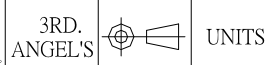
- MATERIAL:
 - Housing: LCP
 - Contact: Copper Alloy
 - Shell: SUS
- Finish:
 - Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - Shell: Nickel under Plated surface layer
- SPECIFICATION:
 - Rate: 30V DC , 1.8 A(VBUS & GND);0.25 A(other pin);
 - Insulator Resistance:100MΩ Min
 - Dielectric Strength: 100V AC
 - Contact Resistance: 30mΩ Max
 - Operation Temperature: -25°C ~ +85°C
 - Insertion Force: 35 N
 - Extraction Force: 10 N

USB 3.0 PIN ASSIGNMENTS

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST



TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	06/19/20		MODLE	USB AF 3.0 DIP 沉板, 板上H:1.36mm L:12.5, 無捲邊反向
CHECKED BY:	DATE	FINISH	DWG NO.	SUA-110E7-30xx-S277
Jacky Chen	06/19/20		PART NO.	SUA-110E7-30xx-S277
APPROVED BY:	DATE	SCALE	SHEET NO.	1 of 1
Tony Kao	06/19/20	1 : 1		

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新圖面	Jack	06/19/20